

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L1	554	leadless with (die near3 pad, contact near3 pad pad)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 08:22
L3	421	1 and metal\$6	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:22
L4	161	3 and encapsulat\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:10
L5	100	4 and etch\$3	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:10
L6	28	5 and ((dicing dic\$3 singulat\$3 cutting sawing saw\$3) with (carrier substrate))	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:13
L7	46	5 and (metal\$6 with etch\$3)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:22
L8	554	leadless with ((die chip 'ic') near3 pad, contact near3 pad pad)	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 08:23
S1	1	"6821821"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 17:15
S2	26	"6093584"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:02
S3	1	"6342730".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:00
S4	1	"6261864".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:01

S5	1	"6136681".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:02
S6	1	"6102710".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:02
S7	1	"5474066".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:02
S8	1	"6001671".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:02
S9	4	"6586677"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:06
S10	16	"6238952"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:19
S11	37	"6081029"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:26
S12	49	"5900676"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 15:03
S13	1	"5849608".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:40
S14	1	"5659200".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:40
S15	1	"5554887".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:41
S16	1	"5309429".PN.	USPAT; USOCR	OR	ON	2005/04/27 10:41
S17	2	"6489557"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:44
S18	100	"6001671"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 10:44
S19	1	"6762118".PN.	USPAT; USOCR	OR	ON	2005/04/27 12:45

S20	1	"6498099".PN.	USPAT; USOCR	OR	ON	2005/04/27 12:45
S21	1	"6194786".PN.	USPAT; USOCR	OR	ON	2005/04/27 12:46
S22	34	"5457340"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 16:33
S23	100	"6001671"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 16:37
S24	0	"10654240"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/27 17:15
S25	1	"10/654240"	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/04/28 07:06

- ☛ L1: (554) leadless with (die near3 pad, contact near3 pad pad)
- ☛ L3: (421) 1 and metal\$6
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- ☛ L7: (46) 5 and (metal\$6 with etch\$3)
- ☛ L8: (554) leadless with ((die chip 'ic') near3 pad, contact near3 pad pad)

Log Failed

SEARCH

Title ☒ Euro's

Default operator: ☒ Highlight all hit terms initially

5 and (metal\$6 with etch\$3)

 BRS form
 IS&R form
 Image
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	U	1	Document I	Issue Dat	Page	Title	Current O	Current X	Retrieval	Inventor	S	C	P	2	3
1	r	r	US 2005006	2005032	19	Semiconductor package	257/787			Low, Andrew Wye	✓	r	r	r	r
2	r	r	US 2005003	2005021	11	Singulation method used	438/689	✓		Lee, Jun Hong et al.	✓	r	r	r	r
3	r	r	US 2005002	2005020	29	Leadless type semicondu	257/678			Tabira, Yukinori et	✓	r	r	r	r
4	r	r	US 2004021	2004110	6	RF seal ring structure	257/758			Tsai, Chaochieh et a	✓	r	r	r	r
5	r	r	US 2004020	2004101	10	Leadless leadframe electr	257/666			Basoor, Suresh et al	✓	r	r	r	r
6	r	r	US 2004016	2004082	8	Leadless leadframe electr	361/715			Mun, Lee Sai et al.	✓	r	r	r	r
7	r	r	US 2003023	2003122	17	Integrated circuit package	257/787			Pedron, Serafin et a	✓	r	r	r	r
8	r	r	US 2003020	2003110	17	Method of forming an ele	324/754			Akram, Salman	✓	r	r	r	r
9	r	r	US 2003020	2003110	17	Method of forming an ele	324/754			Akram, Salman	✓	r	r	r	r
10	r	r	US 2003020	2003103	16	Method of forming an ele	324/755			Akram, Salman	✓	r	r	r	r
11	r	r	US 2003019	2003102	17	Method of forming an ele	438/612			Akram, Salinan	✓	r	r	r	r
12	r	r	US 2003017	2003092	11	Preplated stamped small	257/666	257/676;		Abbott, Donald C.	✓	r	r	r	r
13	r	r	US 2003017	2003091	34	Attachment of surface mo	428/343	428/347;		Stewart, Steven L. e	✓	r	r	r	r
14	r	r	US 2003017	2003091	30	Attachment of surface mo	428/317.7	257/E21.5		Stewart, Steven L. e	✓	r	r	r	r
15	r	r	US 2003012	2003071	18	Method for reconstructin	216/14	257/E21.5		Dlugokecki, Joseph	✓	r	r	r	r
16	r	r	US 2003012	2003071	19	Method for deconstructin	29/827	257/E21.5		Dlugokecki, Joseph	✓	r	r	r	r

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Active

L1: (554) leadless with (die near3 pad, contact near3 pad pad)

L3: (421) 1 and metal\$6

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Failed

Search

DBs

US:PGPUB;USPAT;EPO;JPO

Default operator: OR

Browse

Query

Run's

Highlight all hit terms initially

5 and (metal\$6 with etch\$3)

BRS form

ISAR form

Image

Text

HTML

	U	Document I	Issue Dat	Page	Title	Current O	Current X	Retrieval	Inventor	S	C	P	2	3
17	<input type="checkbox"/>	US 2003012	2003070	7	Seal ring structure for rad	257/678	438/106	✓	Tsai, Chao-Chieh et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
18	<input type="checkbox"/>	US 2003006	2003040	16	Leadless semiconductor p	257/666	257/676;		Chun, DoSung et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
19	<input type="checkbox"/>	US 2002019	2002122	12	SINGULATION METHO	438/460	257/E23.1		Kim, Hyeongno et a	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
20	<input type="checkbox"/>	US 2001001	2001081	17	Leadless plastic chip carri	438/690	257/E23.0		Kwan, Kin Pui et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
21	<input type="checkbox"/>	US 2001000	2001071	20	Leadless plastic chip carri	257/692	257/E23.0		McLellan, Neil et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
22	<input type="checkbox"/>	US 6884663	2005042	18	Method for reconstructin	438/126	438/127	✓	Dlugokecki; Joseph	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
23	<input type="checkbox"/>	US 6882167	2005041	17	Method of forming an ele	324/754	324/765		Akram; Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
24	<input type="checkbox"/>	US 6872661	2005032	16	Leadless plastic chip carri	438/689	438/613	✓	Kwan, Kin Pui et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
25	<input type="checkbox"/>	US 6831472	2004121	16	Method of forming an ele	324/754	324/765		Akram; Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
26	<input type="checkbox"/>	US 6813828	2004110	18	Method for deconstructin	29/827	29/402.01;		Dlugokecki; Joseph	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
27	<input type="checkbox"/>	US 6797541	2004092	14	Leadless semiconductor p	438/111	257/E23.0		Chun, DoSung et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
28	<input type="checkbox"/>	US 6773961	2004081	12	Singulation method used	438/112	438/111;	✓	Lee; Jun Hong et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
29	<input type="checkbox"/>	US 6635957	2003102	15	Leadless plastic chip carri	257/691	257/693;		Kwan, Kin Pui et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
30	<input type="checkbox"/>	US 6610924	2003082	9	Semiconductor package	174/52.4	174/52.2;		Lee; Shih-Chang et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
31	<input type="checkbox"/>	US 6556030	2003042	19	Method of forming an ele	324/754	324/765		Akram; Salinan	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
32	<input type="checkbox"/>	US 6537849	2003032	6	Seal ring structure for rad	438/106	438/637	✓	Tsai, Chao-Chieh et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

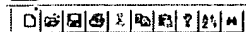
Hit

Details

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FILE



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☐ QRS ☐ US PGPUB ☐ USPAT ☐ EPO ☐ JPO ☐ Burs

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5 and (metal\$6 with etch\$3)

	U	Document I	Issue Dat	Page	Title	Current O	Current X	Retrieval	Inventor	S	C	P	2	3
32	<input type="checkbox"/>	US 6537849	2003032	6	Seal ring structure for rad	438/106	438/637		Tsai; Chao-Chieh et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
33	<input type="checkbox"/>	US 6525405	2003022	23	Leadless semiconductor p	257/666	174/52.3;		Chun; DoSung et al	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
34	<input type="checkbox"/>	US 6489218	2002120	11	Singulation method used	438/460	257/E23.1		Kim; Hyeongno et a	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
35	<input type="checkbox"/>	US 6448107	2002091	13	Pin indicator for leadless	438/106	257/E23.0		Hong; Harry Kam C	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
36	<input type="checkbox"/>	US 6400004	2002060	11	Leadless semiconductor p	257/666	257/670;		Fan; Alex et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
37	<input type="checkbox"/>	US 6312976	2001110	8	Method for manufacturin	438/112	257/666;		Lin; Chun Hung et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
38	<input type="checkbox"/>	US 5700697	1997122	10	Method for packaging an	438/4	257/E21.5		Dlugokecki; Joseph	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
39	<input type="checkbox"/>	US 5650593	1997072	30	Thermally enhanced chip	174/52.4	174/52.2;		McMillan; John R.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
40	<input type="checkbox"/>	US 5612576	1997031	7	Self-opening vent hole in	257/788	257/787;		Wilson; Howard P.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
41	<input type="checkbox"/>	US 5592025	1997010	8	Pad array semiconductor	257/774	257/690;		Clark; Minh-Hien N	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
42	<input type="checkbox"/>	US 5406117	1995041	13	Radiation shielding for in	257/659	257/660;		Dlugokecki; Joseph	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
43	<input type="checkbox"/>	US 5318926	1994060	9	Method for packaging an	29/827	257/E21.5		Dlugokecki; Joseph	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
44	<input type="checkbox"/>	US 5072283	1991121	20	Pre-formed chip carrier c	257/676	257/672;		Bolger; Justin C.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
45	<input type="checkbox"/>	US 4736236	1988040	11	Tape bonding material an	257/672	257/677;		Butt; Sheldon H.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
46	<input type="checkbox"/>	US 4551746	1985110	26	Leadless chip carrier app	257/691	257/700;		Gilbert; Barry K. et	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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